CERTIFICATE OF MAILING

MANTMANT hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to:

Box: Non-Fee Amendment Commissioner for Patents Washington, D.C. 20231

on 04,30,03

Gloria Simmons

In re application of: Shi, et al.

Serial Number: 09/648,777

Filing Date: August 28, 2000

Group No.: 2812

Examiner: Nguyen, Ha T.

....

Title: Process and Material for Low-Cost Flip-Chip Solder Interconnect Structures

Attached are the following documents for filing with the USPTO:

Postcard Amendment Transmittal Form (1 Page) First Response (with Amendments)

In re P	ATENT	application of:	Shi, et ale	Fyaminer: N	Nguyen, Ha T.	
Serial No: 09/648,777						
Filed:	August	28, 2000	MAY 0 6 2003 10	Group No.:	2812	
Title:	Docket No.: 820701-1080 Process and Material for Low-Cost Flip-Chip Solder Interco				820701-1080	aget Strugtures
i i a a a a a a a a a a a a a a a a a a						
AMENDMENT TRANSMITTAL LETTER						
Box: Non-Fee Amendment Commissioner of Patents Washington, D.C. 20231						RECEIVED NAY - 7 2003 ECHNOLOGY CENTLR
Sir:						ED 2003 VILK 2800
Transm	Fransmitted herewith is an amendment in the above-identified application.					
	Response/Amendment Fee as Calculated Below No additional fee is required. Small Entity status has been established. Terminal Disclaimer Corrected Drawings Other:					
			AS AMENDEI	FOR LARGE	ENTITY	
	_	Claims After Amendment	Highest Prev. Paid For	Extra	Rate	Additional Fee
Total Claims		53	- 53	0	x \$18.00	= \$0.00
Indeper Claims		3	- 3	0	x \$84.00	= \$0.00
			Total Addit	tional Fee for th		= \$0.00
A check in the amount of \$ is enclosed. A Credit Card Payment Form PTO-2038 is attached in the amount of \$ The Commissioner is hereby authorized to charge to our Deposit Account No. the amount of \$ for the fee identified above. A duplicate of this Amendment Transmittal Letter is included herewith. The Commissioner is authorized to charge any insufficiencies, and the Commissioner is hereby requested to credit any overpayments to our Deposit Account No. 20-0778.						
Custom	ner No.:	24504		DMAS, KAYDEN, RISDEY, L.L.P.		
Date: <u>F</u>	fori(3	<u>0 2003</u>		Id Deveau, Reg.	•	

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Shi et al.

Serial No.: 09/648,777

Filed: August 28, 2000

For: Process and Material for Low-Cost

Flip-Chip Solder Interconnect Structures

Group Art Unit: 2812

Examiner: Nguyen, HarT

Docket No. 820701-1080

RECEIVED

FIRST RESPONSE (WITH AMENDMENTS)

Commissioner for Patents Washington, D.C. 20231

Sir:

The Office Action mailed January 31, 2003 (Paper No. 8) has been received and carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

AUTHORIZATION TO DEBIT ACCOUNT

It is not believed that extensions of time or fees for net addition of claims are required, beyond those which may otherwise be provided for in documents accompanying this paper. However, in the event that additional extensions of time are necessary to allow consideration of this paper, such extensions are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to deposit account no. 20-0778.